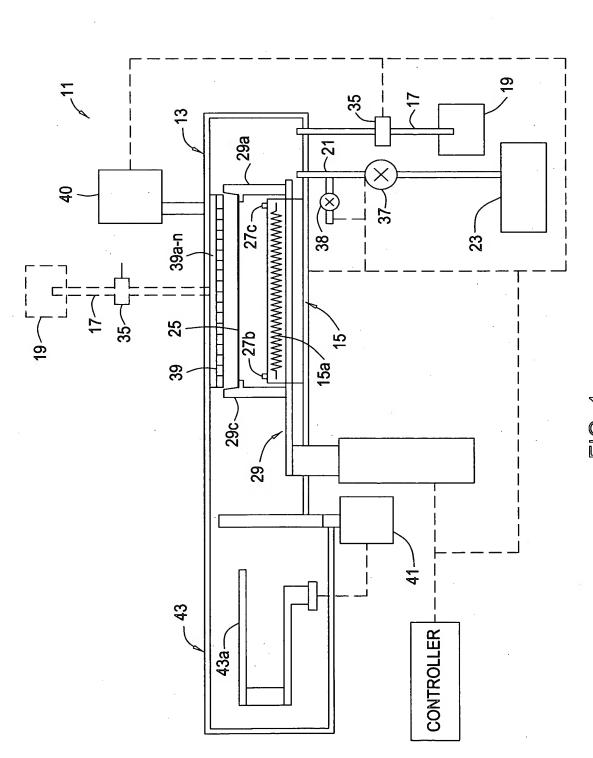
AMAT/1717.C3/CPES/DT/PJS 10/701,387 CONF. NO.: UNKNOWN NOVEMBER 4, 2003 APPLIED MATERIALS METHOD AND APPARATUS FOR HEATING AND COOLING

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APPLICANT: TITLE: SUBSTRATES INVENTOR:

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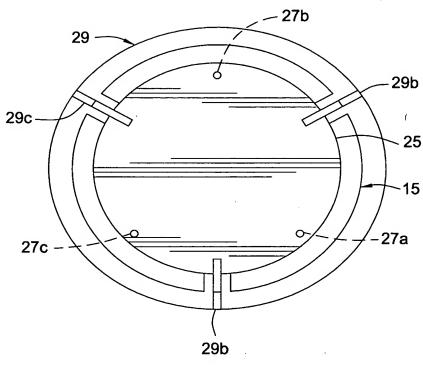


FIG. 2

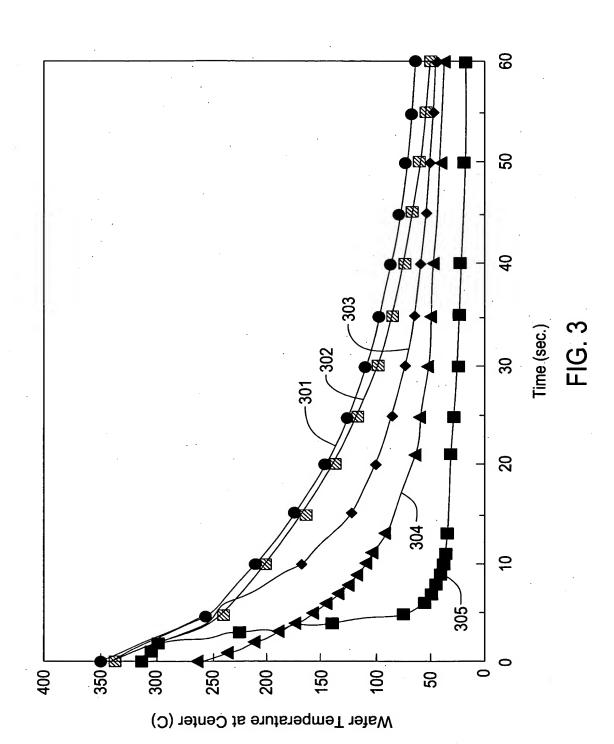
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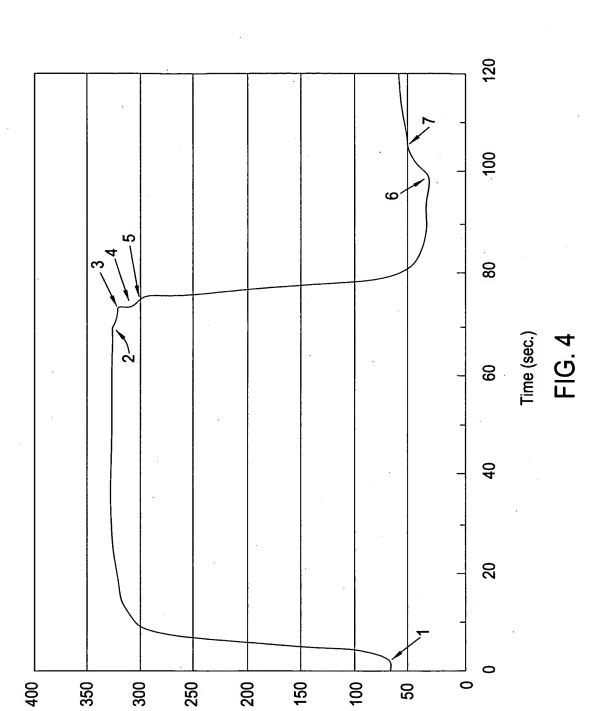
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Wafer Temperature at Center (C)



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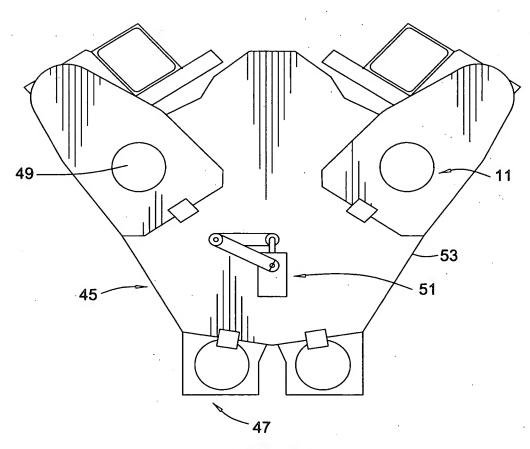


FIG. 5